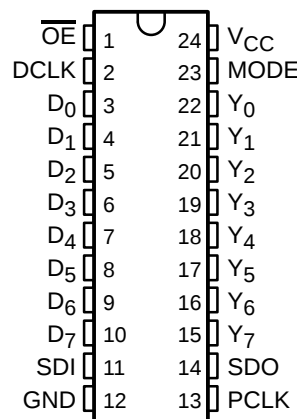


# CY29FCT818T DIAGNOSTIC SCAN REGISTER WITH 3-STATE OUTPUTS

SCCS012B – MAY 1994 – REVISED NOVEMBER 2001

- Function, Pinout, and Drive Compatible With FCT, F Logic, and AM29818
- Reduced  $V_{OH}$  (Typically = 3.3 V) Version of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- 8-Bit Pipeline and Shadow Register
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- CY29FCT818CT
  - 64-mA Output Sink Current
  - 32-mA Output Source Current
- CY29FCT818ATDMB
  - 20-mA Output Sink Current
  - 3-mA Output Source Current
- 3-State Outputs

D, P, Q, OR SO PACKAGE  
(TOP VIEW)



## description

The CY29FCT818T contains a high-speed 8-bit general-purpose data pipeline register and a high-speed 8-bit shadow register. The general-purpose register can be used in an 8-bit-wide data path for a normal system application. The shadow register is designed for applications such as diagnostics in sequential circuits, where it is desirable to load known data at a specific location in the circuit and to read the data at that location.

The shadow register can load data from the output of the device, and can be used as a right-shift register with bit-serial input (SDI) and output (SDO), using DCLK. The data register input is multiplexed to enable loading from the shadow register or from the data input pins, using PCLK. Data can be loaded simultaneously from the shadow register to the pipeline register, and from the pipeline register to the shadow register, provided setup-time and hold-time requirements are satisfied, with respect to the two independent clock inputs.

In a typical application, the general-purpose register in this device replaces an 8-bit data register in the normal data path of a system. The shadow register is placed in an auxiliary bit-serial loop that is used for diagnostics. During diagnostic operation, data is shifted serially into the shadow register, then transferred to the general-purpose register to load a known value into the data path. To read the contents at that point in the data path, the data is transferred from the data register into the shadow register, then shifted serially in the auxiliary diagnostic loop to make it accessible to the diagnostics controller. This data then is compared with the expected value to diagnose faulty operation of the sequential circuit.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# CY29FCT818T

## DIAGNOSTIC SCAN REGISTER

### WITH 3-STATE OUTPUTS

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#### ORDERING INFORMATION

| T <sub>A</sub> | PACKAGE <sup>†</sup> |               | SPEED<br>(ns) | ORDERABLE<br>PART NUMBER | TOP-SIDE<br>MARKING |
|----------------|----------------------|---------------|---------------|--------------------------|---------------------|
| –40°C to 85°C  | DIP – P              | Tube          | 6             | CY29FCT818CTPC           | CY29FCT818CTPC      |
|                | QSOP – Q             | Tape and reel | 6             | CY29FCT818CTQCT          | 29FCT818C           |
|                | SOIC – SO            | Tube          | 6             | CY29FCT818CTSOC          | 29FCT818C           |
|                |                      | Tape and reel | 6             | CY29FCT818CTSOCT         |                     |
| –55°C to 125°C | CDIP – D             | Tube          | 12            | CY29FCT818ATDMB          |                     |

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

#### FUNCTION TABLE

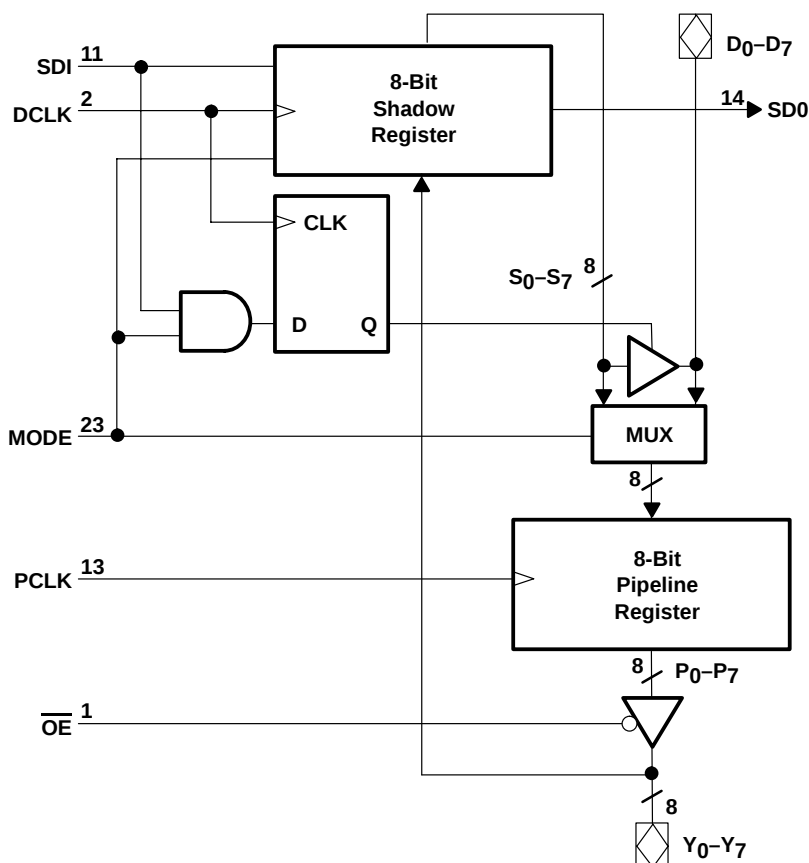
| INPUTS |     |      |      | OUTPUT<br>SDO  | SHADOW<br>REGISTER                                      | PIPELINE<br>REGISTER           | OPERATION                                                           |
|--------|-----|------|------|----------------|---------------------------------------------------------|--------------------------------|---------------------------------------------------------------------|
| MODE   | SDI | DCLK | PCLK |                |                                                         |                                |                                                                     |
| L      | X   | ↑    | X    | S <sub>7</sub> | S <sub>0</sub> ←SDI<br>S <sub>i</sub> ←S <sub>i–1</sub> | NA                             | Serial shift; D <sub>7</sub> –D <sub>0</sub> output disabled        |
| L      | X   | X    | ↑    | S <sub>7</sub> | NA                                                      | P <sub>i</sub> ←D <sub>i</sub> | Load pipeline register from data input                              |
| H      | L   | ↑    | X    | L              | S <sub>i</sub> ←Y <sub>i</sub>                          | NA                             | Load shadow register from Y output                                  |
| H      | H   | ↑    | X    | H              | Hold                                                    | NA                             | Hold shadow register; D <sub>7</sub> –D <sub>0</sub> output enabled |
| H      | X   | X    | ↑    | SDI            | NA                                                      | P <sub>i</sub> ←S <sub>i</sub> | Load pipeline register from shadow register                         |

H = High logic level, L = Low logic level, X = Don't care, ↑ Low-to-high transition, ← = Transfer direction, NA = Not applicable



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**logic diagram**



**absolute maximum rating over operating free-air temperature range (unless otherwise noted)<sup>†</sup>**

|                                                                  |                |
|------------------------------------------------------------------|----------------|
| Supply voltage range to ground potential                         | –0.5 V to 7 V  |
| DC input voltage range                                           | –0.5 V to 7 V  |
| DC output voltage range                                          | –0.5 V to 7 V  |
| DC output current (maximum sink current/pin)                     | 120 mA         |
| Package thermal impedance, $\theta_{JA}$ (see Note 1): P package | 67°C/W         |
| (see Note 2): Q package                                          | 61°C/W         |
| (see Note 2): SO package                                         | 46°C/W         |
| Ambient temperature range with power applied, $T_A$              | –65°C to 135°C |
| Storage temperature range, $T_{Stg}$                             | –65°C to 150°C |

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The package thermal impedance is calculated in accordance with JESD 51-3.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

# CY29FCT818T

## DIAGNOSTIC SCAN REGISTER

### WITH 3-STATE OUTPUTS

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#### recommended operating conditions (see Note 3)

|                                               | CY29FCT818ATDMB |     |     | CY29FCT818T |     |      | UNIT |
|-----------------------------------------------|-----------------|-----|-----|-------------|-----|------|------|
|                                               | MIN             | NOM | MAX | MIN         | NOM | MAX  |      |
| V <sub>CC</sub> Supply voltage                | 4.5             | 5   | 5.5 | 4.75        | 5   | 5.25 | V    |
| V <sub>IH</sub> High-level input voltage      | 2               |     |     | 2           |     |      | V    |
| V <sub>IL</sub> Low-level input voltage       |                 |     | 0.8 |             |     | 0.8  | V    |
| I <sub>OH</sub> High-level output current     |                 |     | –3  |             |     | –32  | mA   |
| I <sub>OL</sub> Low-level output current      |                 |     | 20  |             |     | 64   | mA   |
| T <sub>A</sub> Operating free-air temperature | –55             |     | 125 | –40         |     | 85   | °C   |

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER         | TEST CONDITIONS                                                                                   |                          | CY29FCT818ATDMB |      |      | CY29FCT818T |      |      | UNIT |
|-------------------|---------------------------------------------------------------------------------------------------|--------------------------|-----------------|------|------|-------------|------|------|------|
|                   |                                                                                                   |                          | MIN             | TYP† | MAX  | MIN         | TYP† | MAX  |      |
| V <sub>IK</sub>   | V <sub>CC</sub> = 4.5 V, I <sub>IN</sub> = –18 mA                                                 |                          | –0.7            | –1.2 |      |             |      |      | V    |
|                   | V <sub>CC</sub> = 4.75 V, I <sub>IN</sub> = –18 mA                                                |                          |                 |      |      | –0.7        | –1.2 |      |      |
| V <sub>OH</sub>   | V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = –3 mA                                                  |                          | 2.4             | 3.3  |      |             |      |      | V    |
|                   | V <sub>CC</sub> = 4.75 V                                                                          | I <sub>OH</sub> = –32 mA |                 |      |      | 2           |      |      |      |
|                   |                                                                                                   | I <sub>OH</sub> = –15 mA |                 |      |      | 2.4         | 3.3  |      |      |
| V <sub>OL</sub>   | V <sub>CC</sub> = 4.5 V, I <sub>OL</sub> = 20 mA                                                  |                          | 0.3             | 0.55 |      |             |      |      | V    |
|                   | V <sub>CC</sub> = 4.75 V, I <sub>OL</sub> = 64 mA                                                 |                          |                 |      |      | 0.3         | 0.55 |      |      |
| V <sub>hys</sub>  | All inputs                                                                                        |                          | 0.2             |      |      | 0.2         |      |      | V    |
| I <sub>I</sub>    | V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = V <sub>CC</sub>                                        |                          |                 |      | 5    |             |      |      | μA   |
|                   | V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = V <sub>CC</sub>                                       |                          |                 |      |      |             |      | 5    |      |
| I <sub>IH</sub>   | V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 2.7 V                                                  |                          |                 |      | ±1   |             |      |      | μA   |
|                   | V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = 2.7 V                                                 |                          |                 |      |      |             |      | ±1   |      |
| I <sub>IL</sub>   | V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0.5 V                                                  |                          |                 |      | ±1   |             |      |      | μA   |
|                   | V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = 0.5 V                                                 |                          |                 |      |      |             |      | ±1   |      |
| I <sub>OZH</sub>  | V <sub>CC</sub> = 5.5 V, V <sub>OUT</sub> = 2.7 V                                                 |                          |                 |      | 10   |             |      |      | μA   |
|                   | V <sub>CC</sub> = 5.25 V, V <sub>OUT</sub> = 2.7 V                                                |                          |                 |      |      |             |      | 10   |      |
| I <sub>OZL</sub>  | V <sub>CC</sub> = 5.5 V, V <sub>OUT</sub> = 0.5 V                                                 |                          |                 |      | –10  |             |      |      | μA   |
|                   | V <sub>CC</sub> = 5.25 V, V <sub>OUT</sub> = 0.5 V                                                |                          |                 |      |      |             |      | –10  |      |
| I <sub>OS</sub> ‡ | V <sub>CC</sub> = 5.5 V, V <sub>OUT</sub> = 0 V                                                   |                          | –60             | –120 | –225 |             |      |      | mA   |
|                   | V <sub>CC</sub> = 5.25 V, V <sub>OUT</sub> = 0 V                                                  |                          |                 |      |      | –60         | –120 | –225 |      |
| I <sub>off</sub>  | V <sub>CC</sub> = 0 V, V <sub>OUT</sub> = 4.5 V                                                   |                          |                 |      | ±1   |             |      | ±1   | μA   |
| I <sub>CC</sub>   | V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> ≤ 0.2 V, V <sub>IN</sub> ≥ V <sub>CC</sub> – 0.2 V       |                          | 0.2             | 1.5  |      |             |      |      | mA   |
|                   | V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> ≤ 0.2 V, V <sub>IN</sub> ≥ V <sub>CC</sub> – 0.2 V      |                          |                 |      |      | 0.2         | 1.5  |      |      |
| ΔI <sub>CC</sub>  | V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 3.4 V <sup>§</sup> , f <sub>1</sub> = 0, Outputs open  |                          | 0.5             | 2    |      |             |      |      | mA   |
|                   | V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> = 3.4 V <sup>§</sup> , f <sub>1</sub> = 0, Outputs open |                          |                 |      |      | 0.5         | 2    |      |      |

† Typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

§ Per TTL-driven input (V<sub>IN</sub> = 3.4 V); all other inputs at V<sub>CC</sub> or GND



**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)**

| PARAMETER                  | TEST CONDITIONS                                                                                                                                     |                                                                                    |                                                        | CY29FCT818ATDMB |      |      | CY29FCT818T |      |      | UNIT       |
|----------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------|--------------------------------------------------------|-----------------|------|------|-------------|------|------|------------|
|                            |                                                                                                                                                     |                                                                                    |                                                        | MIN             | TYP† | MAX  | MIN         | TYP† | MAX  |            |
| $I_{CCD}^{\dagger\dagger}$ | $V_{CC} = 5.5$ V, Outputs open, One input switching at 50% duty cycle, $\overline{OE} = GND$ , $V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V  |                                                                                    |                                                        |                 |      | 0.25 |             |      |      | mA/<br>MHz |
|                            | $V_{CC} = 5.25$ V, Outputs open, One input switching at 50% duty cycle, $\overline{OE} = GND$ , $V_{IN} \leq 0.2$ V or $V_{IN} \geq V_{CC} - 0.2$ V |                                                                                    |                                                        |                 |      |      |             | 0.25 |      |            |
| $I_C^{\#}$                 | $V_{CC} = 5.5$ V,<br>Outputs open,<br>$f_0 = 10$ MHz,<br>$\overline{OE} = GND$                                                                      | One bit switching<br>at $f_1 = 5$ MHz<br>at 50% duty cycle                         | $V_{IN} \leq 0.2$ V or<br>$V_{IN} \geq V_{CC} - 0.2$ V |                 |      | 5.3  |             |      |      | mA         |
|                            |                                                                                                                                                     |                                                                                    | $V_{IN} = 3.4$ V or GND                                |                 |      | 7.3  |             |      |      |            |
|                            |                                                                                                                                                     | Eight bits and four<br>controls switching<br>at $f_1 = 5$ MHz<br>at 50% duty cycle | $V_{IN} \leq 0.2$ V or<br>$V_{IN} \geq V_{CC} - 0.2$ V |                 |      | 17.8 |             |      |      |            |
|                            |                                                                                                                                                     |                                                                                    | $V_{IN} = 3.4$ V or GND                                |                 |      | 30.8 |             |      |      |            |
|                            | $V_{CC} = 5.25$ V,<br>Outputs open,<br>$f_0 = 10$ MHz,<br>$\overline{OE} = GND$                                                                     | One bit switching<br>at $f_1 = 5$ MHz<br>at 50% duty cycle                         | $V_{IN} \leq 0.2$ V or<br>$V_{IN} \geq V_{CC} - 0.2$ V |                 |      |      |             |      | 5.3  |            |
|                            |                                                                                                                                                     |                                                                                    | $V_{IN} = 3.4$ V or GND                                |                 |      |      |             |      | 7.3  |            |
|                            |                                                                                                                                                     | Eight bits and four<br>controls switching<br>at $f_1 = 5$ MHz<br>at 50% duty cycle | $V_{IN} \leq 0.2$ V or<br>$V_{IN} \geq V_{CC} - 0.2$ V |                 |      |      |             |      | 17.8 |            |
|                            |                                                                                                                                                     |                                                                                    | $V_{IN} = 3.4$ V or GND                                |                 |      |      |             |      | 30.8 |            |
| $C_i$                      |                                                                                                                                                     |                                                                                    |                                                        |                 | 5    | 10   |             | 5    | 10   | pF         |
| $C_0$                      |                                                                                                                                                     |                                                                                    |                                                        |                 | 9    | 12   |             | 9    | 12   | pF         |

† Typical values are at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$ .

†† This parameter is derived for use in total power-supply calculations.

#  $I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

$I_C$  = Total supply current

$I_{CC}$  = Power-supply current with CMOS input levels

$\Delta I_{CC}$  = Power-supply current for a TTL high input ( $V_{IN} = 3.4$  V)

$D_H$  = Duty cycle for TTL inputs high

$N_T$  = Number of TTL inputs at  $D_H$

$I_{CCD}$  = Dynamic current caused by an input transition pair (HLH or LHL)

$f_0$  = Clock frequency for registered devices, otherwise zero

$f_1$  = Input signal frequency

$N_1$  = Number of inputs changing at  $f_1$

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the  $I_{CC}$  formula.

# CY29FCT818T

## DIAGNOSTIC SCAN REGISTER

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

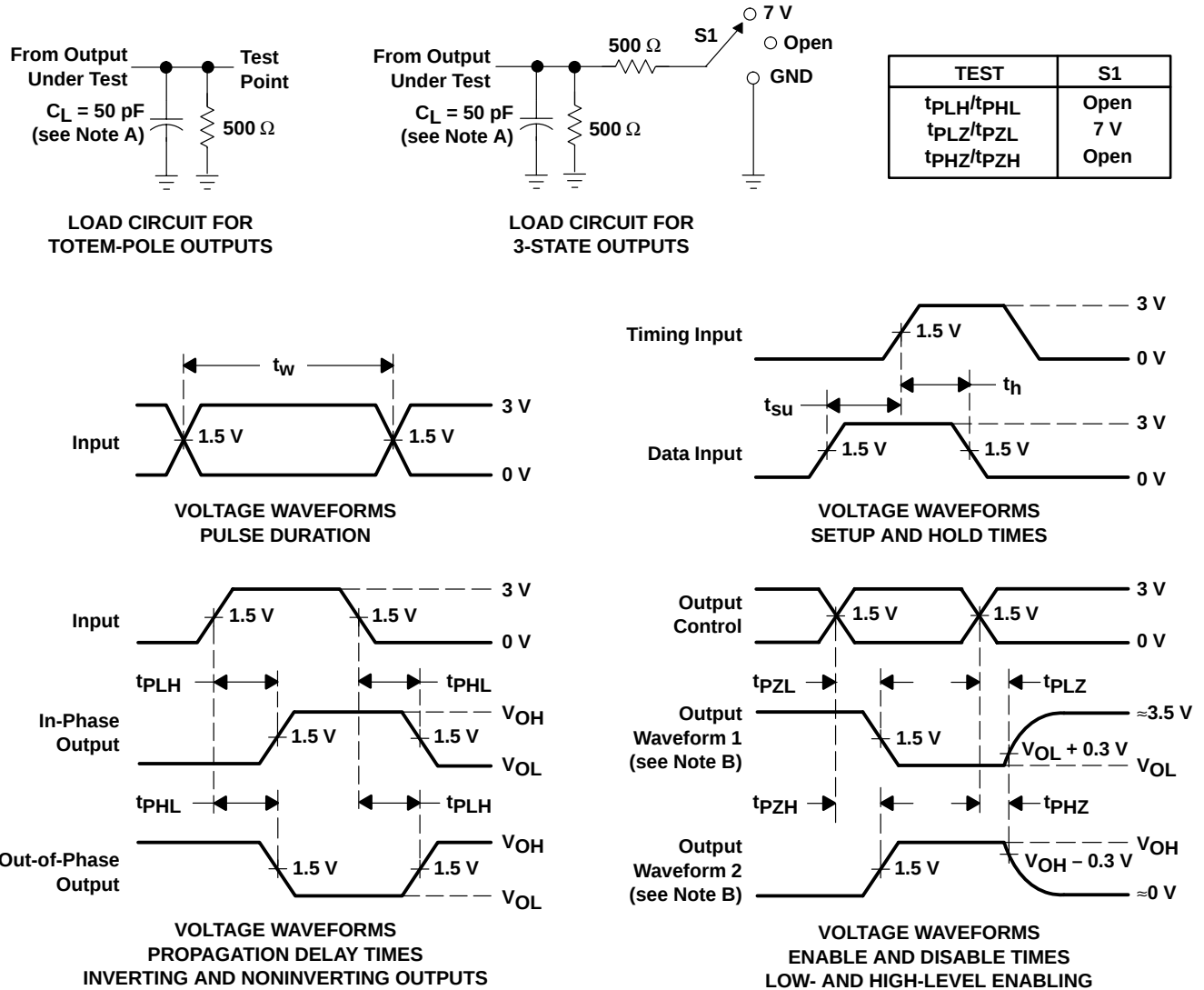
| PARAMETER           |                   | CY29FCT818AT |     | CY29FCT818CT |     | UNIT |
|---------------------|-------------------|--------------|-----|--------------|-----|------|
|                     |                   | MIN          | MAX | MIN          | MAX |      |
| $t_w$ Pulse width   | PCLK high and low | 15           |     | 5            |     | ns   |
|                     | DCLK high and low | 25           |     | 5            |     |      |
| $t_{su}$ Setup time | D before PCLK↑    | 6            |     | 2            |     | ns   |
|                     | MODE before PCLK↑ | 15           |     | 3.5          |     |      |
|                     | Y before DCLK↑    | 5            |     | 2            |     |      |
|                     | MODE before DCLK↑ | 12           |     | 3.5          |     |      |
|                     | SDI before DCLK↑  | 10           |     | 3.5          |     |      |
|                     | DCLK before PCLK↑ | 15           |     | 3.5          |     |      |
|                     | PCLK before DCLK↑ | 45           |     | 8.5          |     |      |
| $t_h$ Hold time     | D after PCLK↑     | 2            |     | 1.5          |     | ns   |
|                     | MODE after PCLK↑  | 0            |     | 0            |     |      |
|                     | Y after DCLK↑     | 5            |     | 1.5          |     |      |
|                     | MODE after DCLK↑  | 5            |     | 1.5          |     |      |
|                     | SDI after DCLK↑   | 0            |     | 0            |     |      |

switching characteristics over operating free-air temperature range (see Figure 1)

| PARAMETER | FROM<br>(INPUT) | TO<br>(OUTPUT) | CY29FCT818AT |     | CY29FCT818CT |     | UNIT |
|-----------|-----------------|----------------|--------------|-----|--------------|-----|------|
|           |                 |                | MIN          | MAX | MIN          | MAX |      |
| $t_{pd}$  | PCLK            | Y              |              | 12  |              | 6   | ns   |
|           | MODE            | SDO            |              | 18  |              | 7.2 |      |
|           | SDI             | SDO            |              | 18  |              | 7.1 |      |
|           | DCLK            | SDO            |              | 30  |              | 7.2 |      |
| $t_{pZL}$ | $\overline{OE}$ | Y              |              | 20  |              | 8   | ns   |
|           | DCLK            | D              |              | 35  |              | 9   |      |
| $t_{pZH}$ | $\overline{OE}$ | Y              |              | 20  |              | 8.5 | ns   |
|           | DCLK            | D              |              | 30  |              | 9   |      |
| $t_{PLZ}$ | $\overline{OE}$ | Y              |              | 20  |              | 5.5 | ns   |
|           | DCLK            | D              |              | 45  |              | 5.5 |      |
| $t_{PHZ}$ | $\overline{OE}$ | Y              |              | 30  |              | 8   | ns   |
|           | DCLK            | D              |              | 90  |              | 8   |      |



## PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

| Orderable Device   | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup>    | Lead/<br>Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples<br>(Requires Login) |
|--------------------|-----------------------|--------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| 5962-9682701Q3A    | ACTIVE                | LCCC         | FK              | 28   | 1           | TBD                        | POST-PLATE           | N / A for Pkg Type           |                             |
| 5962-9682701QLA    | ACTIVE                | CDIP         | JT              | 24   | 1           | TBD                        | Call TI              | Call TI                      |                             |
| CY29FCT818ATDMB    | ACTIVE                | CDIP         | JT              | 24   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CY29FCT818CTQC     | PREVIEW               | SSOP         | DBQ             | 24   | 55          | TBD                        | Call TI              | Call TI                      |                             |
| CY29FCT818CTSOCT   | ACTIVE                | SOIC         | DW              | 24   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CY29FCT818CTSOCTE4 | ACTIVE                | SOIC         | DW              | 24   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CY29FCT818CTSOCTG4 | ACTIVE                | SOIC         | DW              | 24   | 2000        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


|    |                                                           |
|----|-----------------------------------------------------------|
| A0 | Dimension designed to accommodate the component width     |
| B0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

| Device           | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CY29FCT818CTSOCT | SOIC         | DW              | 24   | 2000 | 330.0              | 24.4               | 10.75   | 15.7    | 2.7     | 12.0    | 24.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



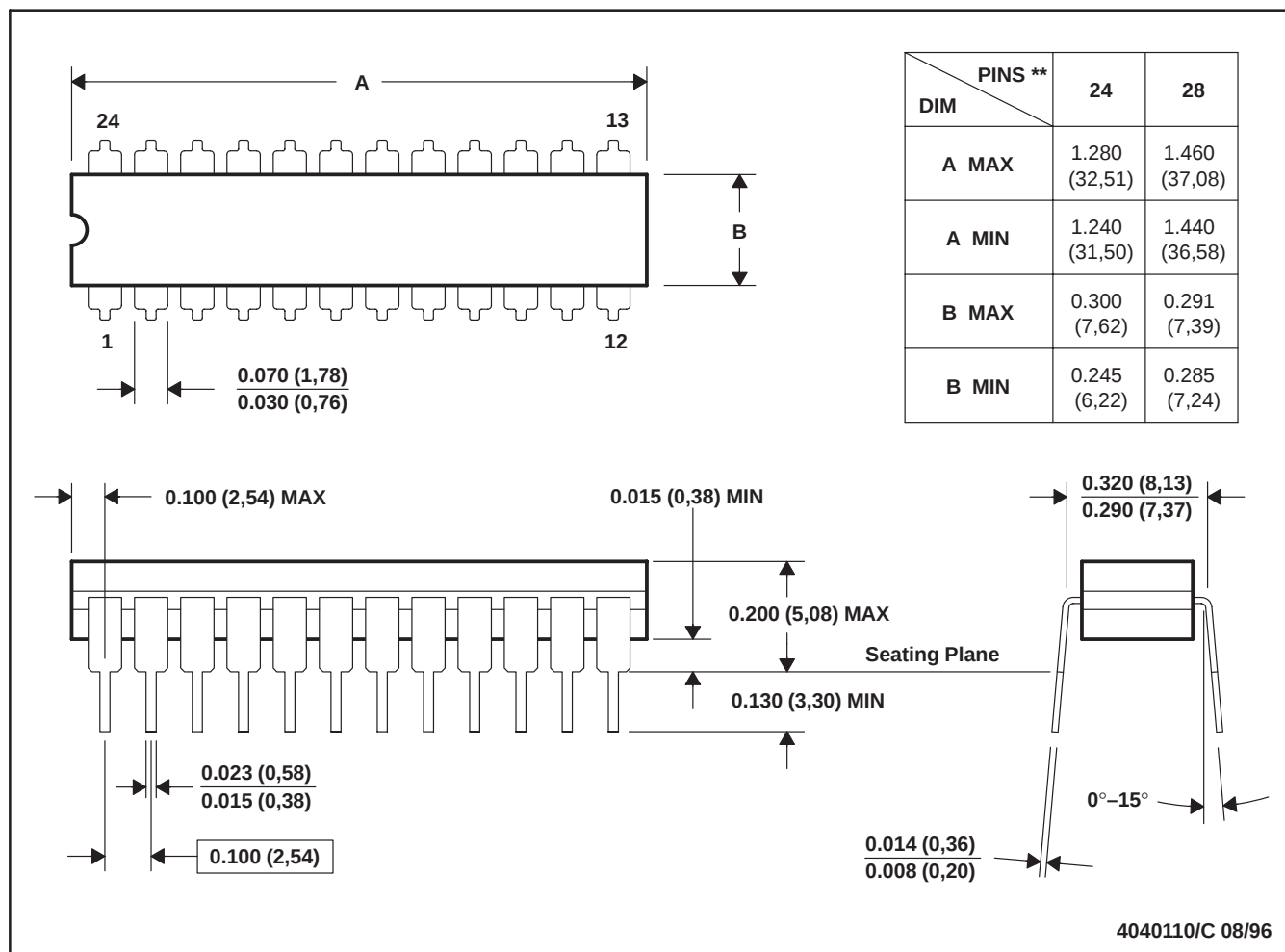
\*All dimensions are nominal

| Device           | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CY29FCT818CTSOCT | SOIC         | DW              | 24   | 2000 | 367.0       | 367.0      | 45.0        |

## JT (R-GDIP-T\*\*)

## CERAMIC DUAL-IN-LINE

24 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification.  
 E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF<br>TERMINALS<br>** | A                |                  | B                |                  |
|---------------------------|------------------|------------------|------------------|------------------|
|                           | MIN              | MAX              | MIN              | MAX              |
| 20                        | 0.342<br>(8,69)  | 0.358<br>(9,09)  | 0.307<br>(7,80)  | 0.358<br>(9,09)  |
| 28                        | 0.442<br>(11,23) | 0.458<br>(11,63) | 0.406<br>(10,31) | 0.458<br>(11,63) |
| 44                        | 0.640<br>(16,26) | 0.660<br>(16,76) | 0.495<br>(12,58) | 0.560<br>(14,22) |
| 52                        | 0.740<br>(18,78) | 0.761<br>(19,32) | 0.495<br>(12,58) | 0.560<br>(14,22) |
| 68                        | 0.938<br>(23,83) | 0.962<br>(24,43) | 0.850<br>(21,6)  | 0.858<br>(21,8)  |
| 84                        | 1.141<br>(28,99) | 1.165<br>(29,59) | 1.047<br>(26,6)  | 1.063<br>(27,0)  |

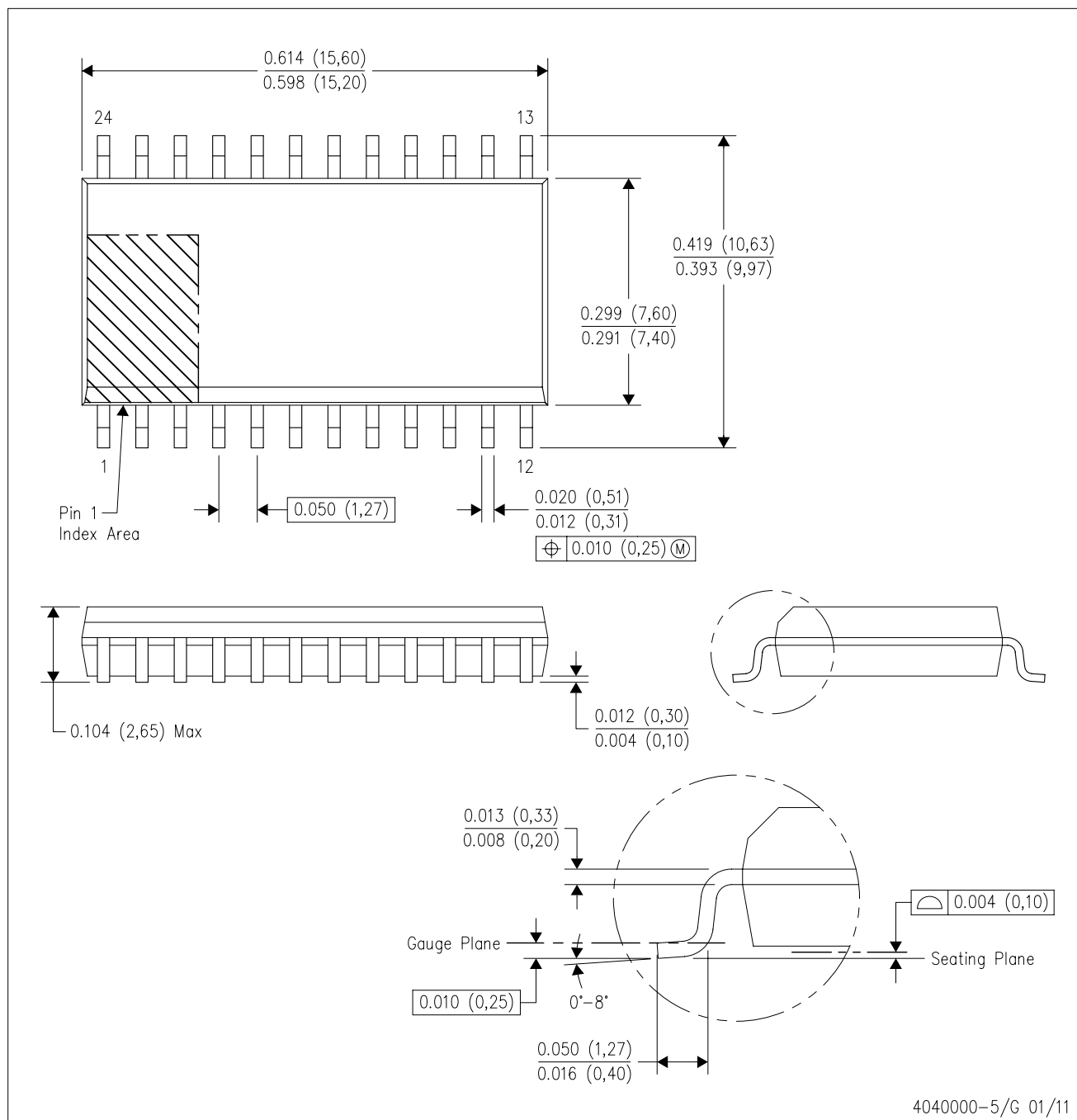


4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

DW (R-PDSO-G24)

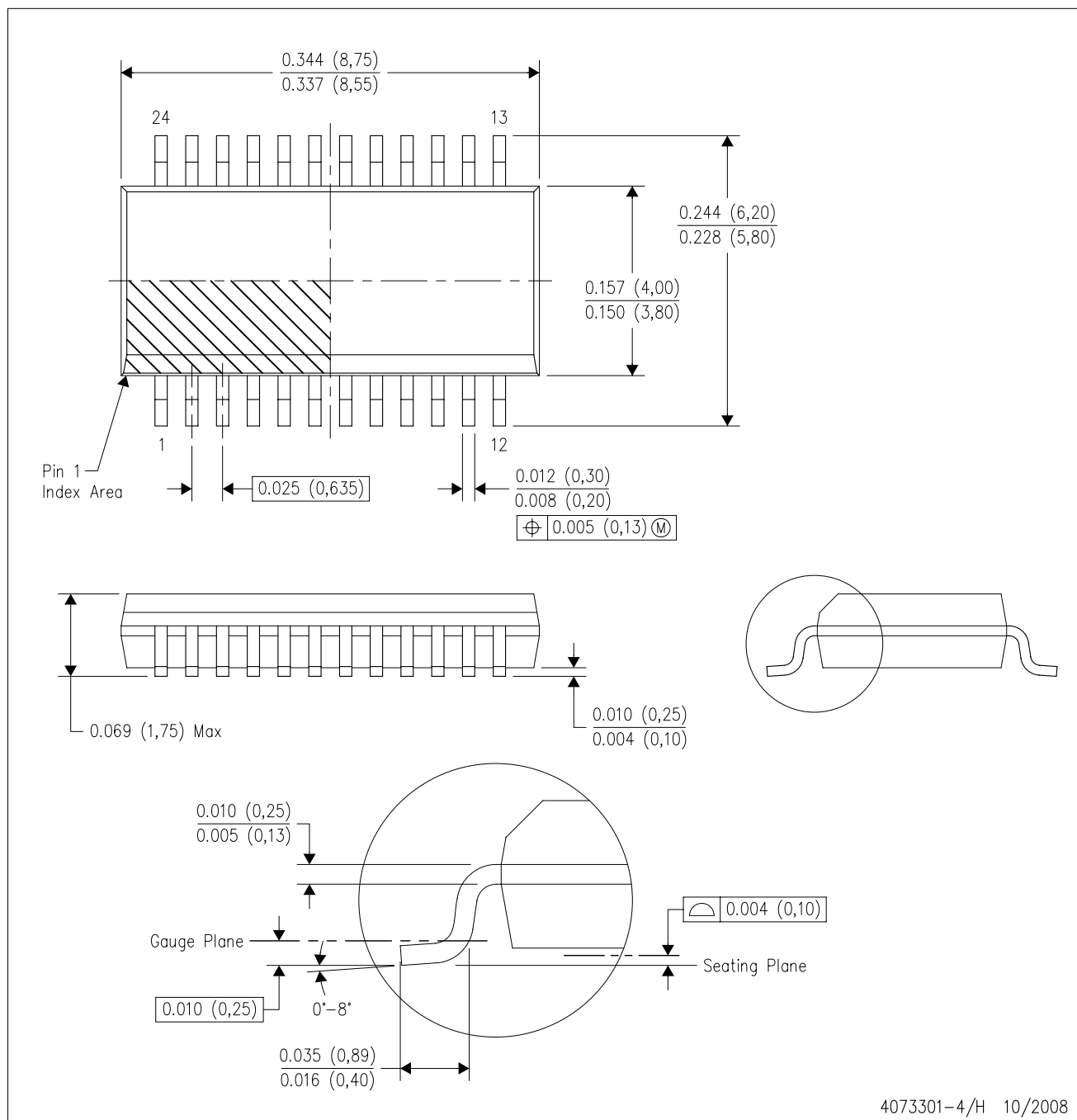
## PLASTIC SMALL OUTLINE



- NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.  
B. This drawing is subject to change without notice.  
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).  
D. Falls within JEDEC MS-013 variation AD.

DBQ (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - D. Falls within JEDEC MO-137 variation AE.

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|                               |                                                                                          |
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